

/ Descriptions

P-Channel Enhancement Mode Field Effect Transistor in a SOP-8 Plastic Package.

/ Features

$V_{DS} (V) = -30V$ $I_D = -16A$ ($V_{GS} = \pm 20V$)

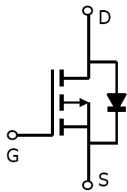
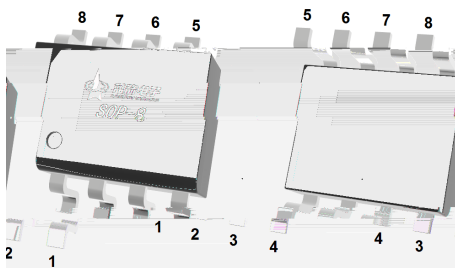
$R_{DS(ON)}@-10V \leq 8.0m\Omega$ (Typ. 7.0m Ω)

$R_{DS(ON)}@-4.5V \leq 15m\Omega$ (Typ. 10.3m Ω)

HF Product.

/ Applications

Power Management in Notebook computer, Portable Equipment and Battery powered systems.

/ Equivalent Circuit**/ Pinning**

PIN1	S	PIN 2	S	PIN 3	S	PIN 4	G
PIN 5	D	PIN 6	D	PIN 7	D	PIN 8	D

/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	-30	V
Drain Current - Continuous		I _D	-16	A
Drain Current – Pulsed		I _{DM}	-65	A
Gate-Source Voltage		V _{GS}	±20	V
Power Dissipation		P _D	3	W
Single Pulse Avalanche Energy(L=0.5mH)		E _{AS}	360	mJ
Avalanche Current(L=0.5mH)		I _{AS}	-30	A
Junction and Storage Temperature Range		T _j , T _{stg}	-55 to 150	
Thermal resistance, junction - ambient	t ≤ 10s	R _{θJA}	41.7	/ W
	Steady-State		75	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = -250\mu A$ $V_{GS} = 0V$	-30	-35		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30V$ $V_{GS} = 0V$			-1	μA
Gate-Body leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ $I_D = -250\mu A$	-1	-1.5	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS} = -10V, I_D = -10A$		7.0	8	m
		$V_{GS} = -4.5V, I_D = -8A$		10.3	15	
Diode Forward Voltage	V_{SD}	$I_S = -1A, V_{GS} = 0V$			-1.2	V
Input Capacitance	C_{iss}	$V_{DS} = -25V$ $V_{GS} = 0V$ $f = 1.0MHz$		3260		pF
Output Capacitance	C_{oss}			335		
Reverse Transfer Capacitance	C_{rss}			330		
Gate resistance	R_g	$V_{GS} = 0V$ $V_{DS} = 0V$ $f = 1MHz$		5.6		Ω
Total Gate Charge	$Q_{g(10V)}$	$V_{GS} = -10V, V_{DS} = -15V,$ $I_D = -20A$		51		nC
Total Gate Charge	$Q_{g(4.5V)}$			32		
Gate Source Charge	Q_{gs}			11		
Gate Drain Charge	Q_{gd}			13		

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	t _{d(on)}	V _{GS} =-10V V _{DS} =-15V R _L =0.75Ω R _{GEN} =3Ω		12.5		ns
Turn-On Rise Time	t _r			19		
Turn-Off Delay Time	t _{d(off)}			125		
Turn-Off Fall Time	t _f			67		

/ Electrical Characteristic Curve

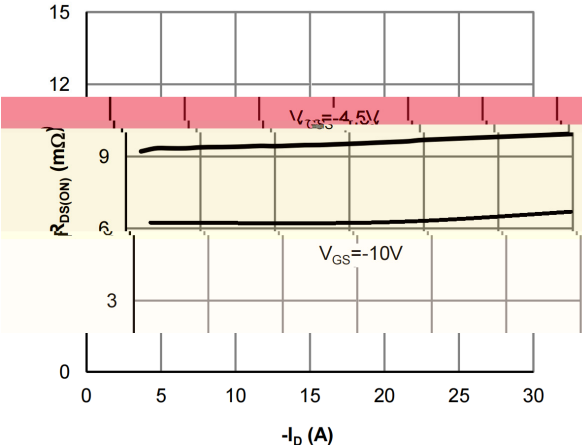
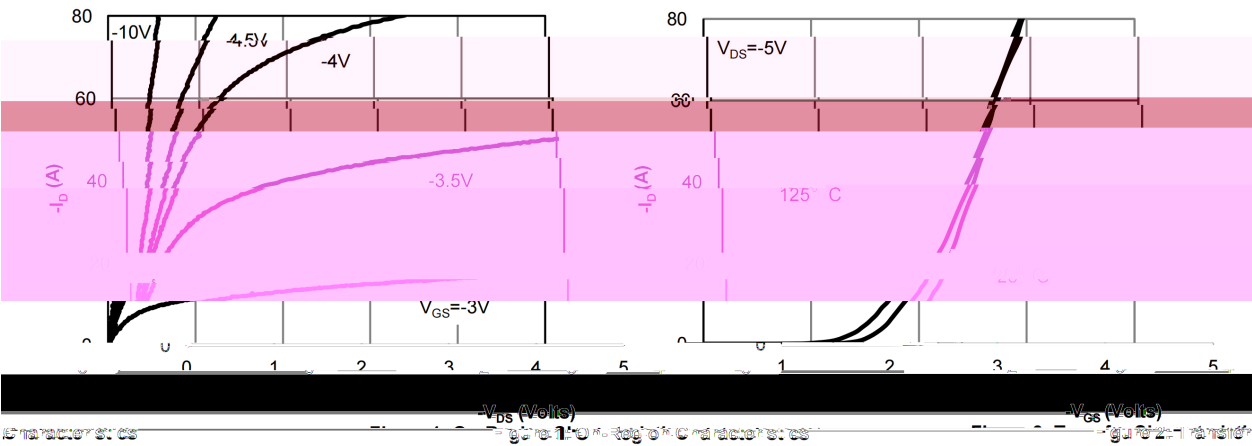


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

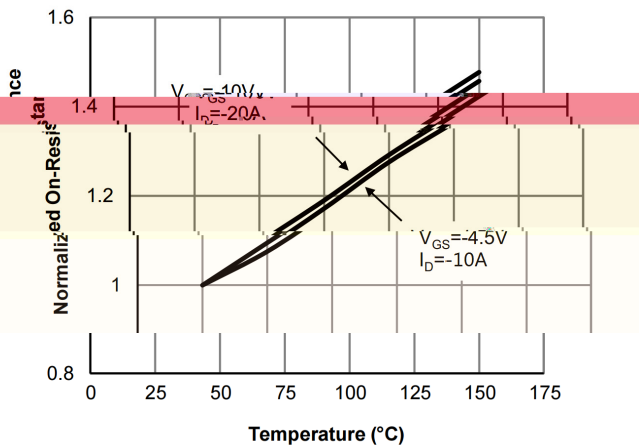


Figure 4: On-Resistance vs. Junction Temperature

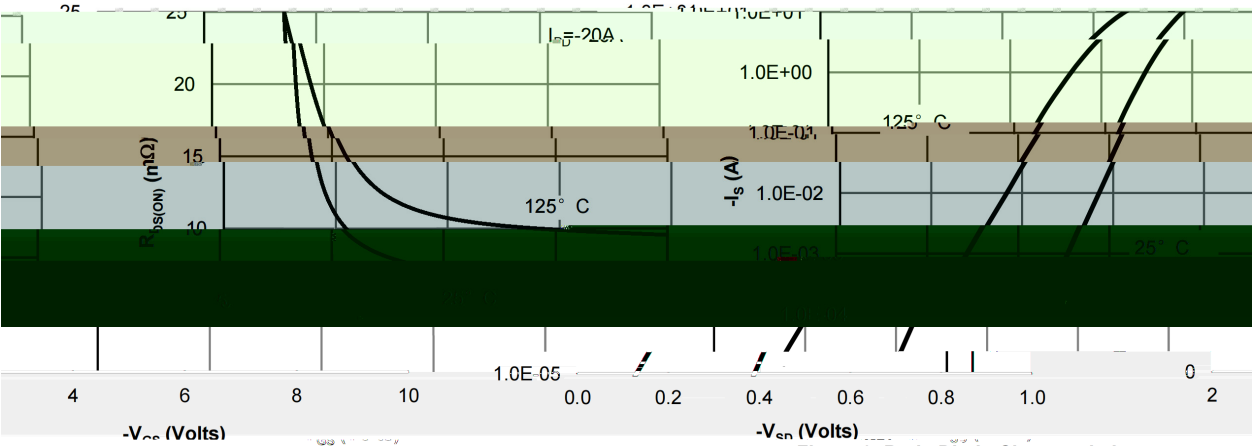


Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

/ Electrical Characteristic Curve

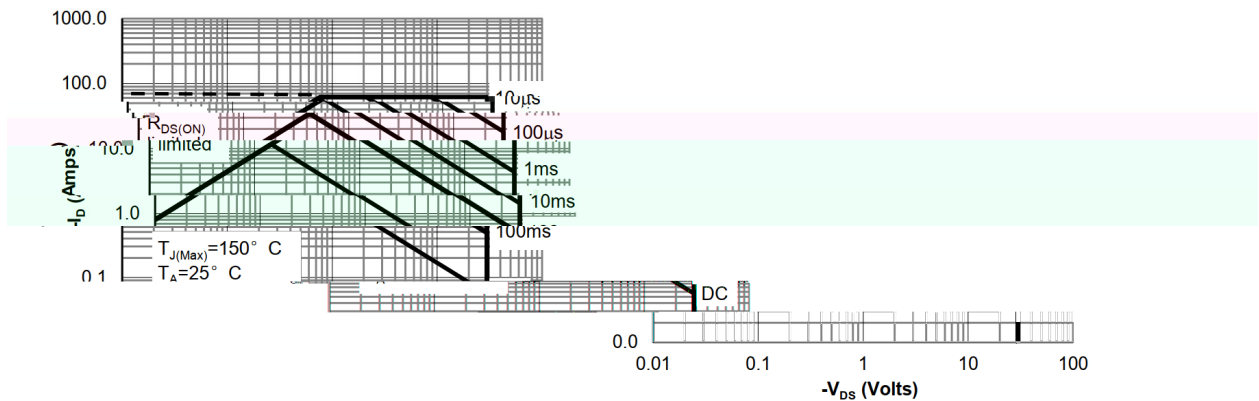
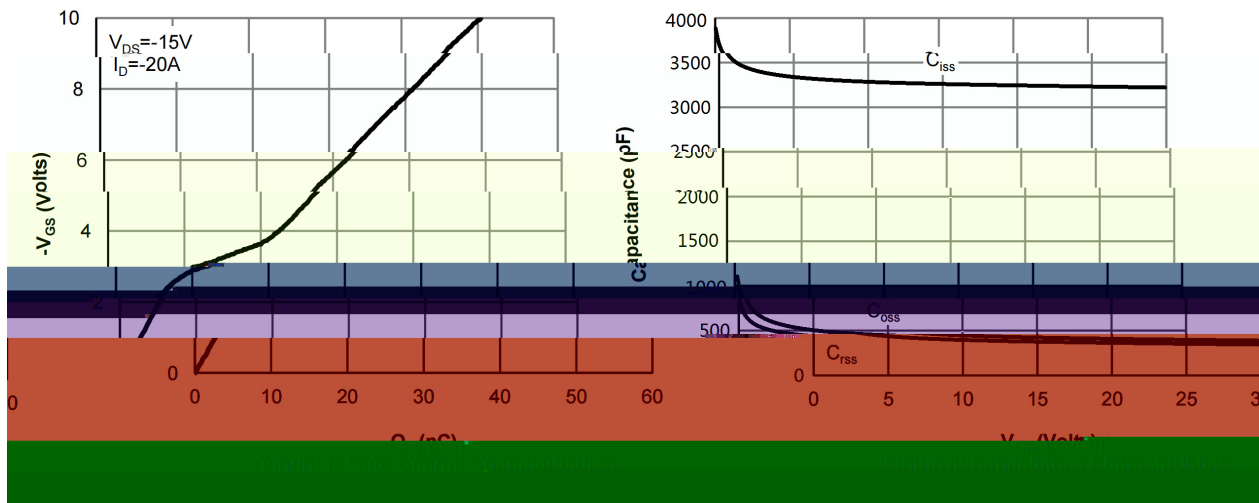


Figure 9: Maximum Forward Biased Safe Operating Area

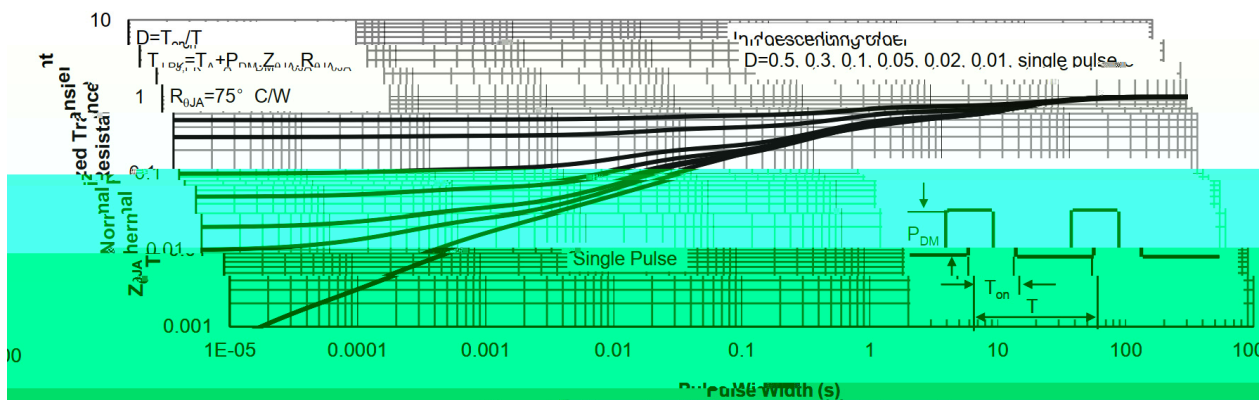
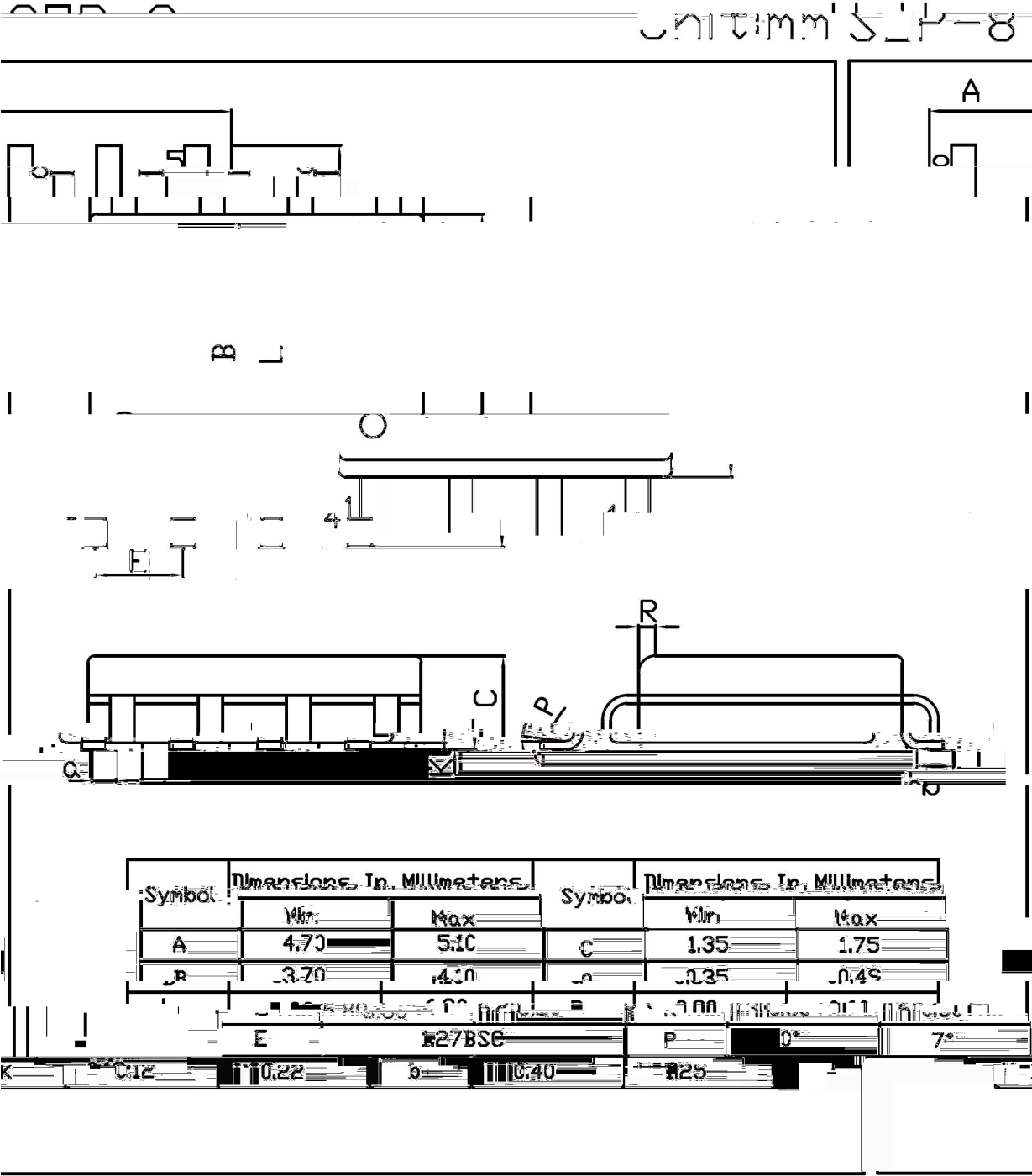
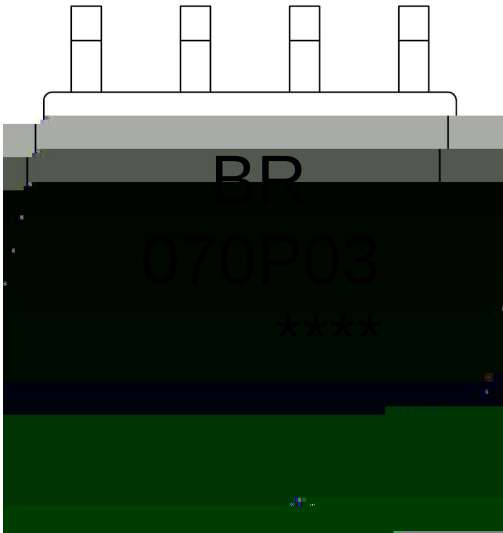


Figure 10: Normalized Maximum Transient Thermal Impedance

/ Package Dimensions



/ Marking Instructions



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Note:

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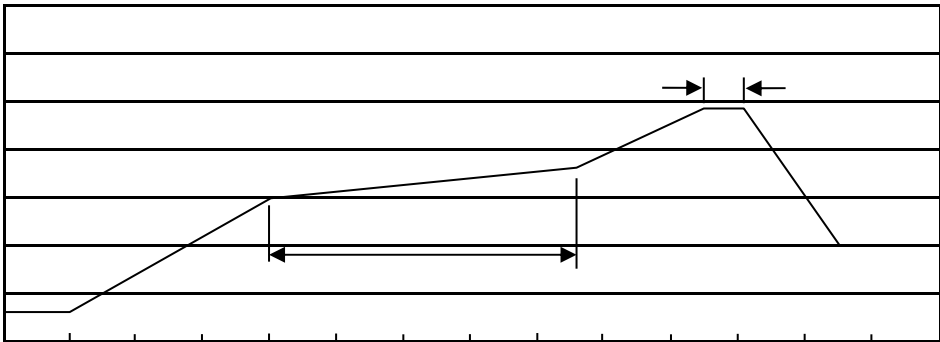
****:

Company Code

Product Type Code

Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



- 1

150 180

60 90sec;
- 2

245 5

5 0.5sec;
- 3

2 10 /sec.
- Note:
1.Preheating:150~180 , Time:60~90sec.
2.Peak Temp.:245 5 , Duration:5 0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOP/ESOP-8	4,000	2	8,000	6	48,000	13 ×12	360×360×50	380×335×366

/ Notices